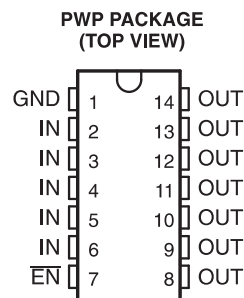
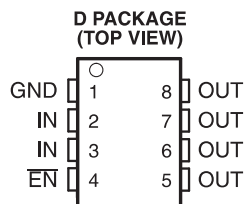


## POWER-DISTRIBUTION SWITCHES

### FEATURES

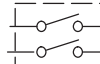
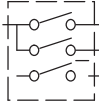
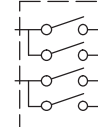
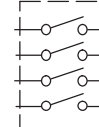
- 33-m $\Omega$  (5-V Input) High-Side MOSFET Switch
- Short-Circuit and Thermal Protection
- Operating Range . . . 2.7 V to 5.5 V
- Logic-Level Enable Input
- Typical Rise Time. . . 6.1 ms
- Undervoltage Lockout
- Maximum Standby Supply Current. . . 10  $\mu$ A
- No Drain-Source Back-Gate Diode
- Available in 8-pin SOIC and 14-Pin TSSOP Packages
- Ambient Temperature Range,  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$
- 2-kV Human-Body-Model, 200-V Machine-Model ESD Protection



### DESCRIPTION

The TPS201xA family of power distribution switches is intended for applications where heavy capacitive loads and short circuits are likely to be encountered. These devices are 50-m $\Omega$  N-channel MOSFET high-side power switches. The switch is controlled by a logic enable compatible with 5-V logic and 3-V logic. Gate drive is provided by an internal charge pump designed to control the power-switch rise times and fall times to minimize current surges during switching. The charge pump requires no external components and allows operation from supplies as low as 2.7 V.

When the output load exceeds the current-limit threshold or a short is present, the TPS201xA limits the output current to a safe level by switching into a constant-current mode. When continuous heavy overloads and short circuits increase the power dissipation in the switch, causing the junction temperature to rise, a thermal protection circuit shuts off the switch to prevent damage. Recovery from a thermal shutdown is automatic once the device has cooled sufficiently. Internal circuitry ensures the switch remains off until valid input voltage is present.

| GENERAL SWITCH CATALOG                                                              |                                                                                                                                                                                             |                                                                                                                                         |                                                                                                          |                                                                                                        |                                                                                       |                                                                                                          |
|-------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------|
| 33 m $\Omega$ , single                                                              | 80 m $\Omega$ , single                                                                                                                                                                      | 80 m $\Omega$ , dual                                                                                                                    | 80 m $\Omega$ , dual                                                                                     | 80 m $\Omega$ , triple                                                                                 | 80 m $\Omega$ , quad                                                                  | 80 m $\Omega$ , quad                                                                                     |
|  |                                                                                                          |                                                      |                       |                    |  |                     |
| TPS201xA 0.2 A - 2 A<br>TPS202x 0.2 A - 2 A<br>TPS203x 0.2 A - 2 A                  | TPS2014 600 mA<br>TPS2015 1 A<br>TPS2041B 500 mA<br>TPS2051B 500 mA<br>TPS2045A 250 mA<br>TPS2049 100 mA<br>TPS2055A 250 mA<br>TPS2061 1 A<br>TPS2065 1 A<br>TPS2068 1.5 A<br>TPS2069 1.5 A | TPS2042B 500 mA<br>TPS2052B 500 mA<br>TPS2046B 250 mA<br>TPS2056 250 mA<br>TPS2062 1 A<br>TPS2066 1 A<br>TPS2060 1.5 A<br>TPS2064 1.5 A | TPS2080 500 mA<br>TPS2081 500 mA<br>TPS2082 500 mA<br>TPS2090 250 mA<br>TPS2091 250 mA<br>TPS2092 250 mA | TPS2043B 500 mA<br>TPS2053B 500 mA<br>TPS2047B 250 mA<br>TPS2057A 250 mA<br>TPS2063 1 A<br>TPS2067 1 A | TPS2044B 500 mA<br>TPS2054B 500 mA<br>TPS2048A 250 mA<br>TPS2058 250 mA               | TPS2085 500 mA<br>TPS2086 500 mA<br>TPS2087 500 mA<br>TPS2095 250 mA<br>TPS2096 250 mA<br>TPS2097 250 mA |



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



## DETAILED DESCRIPTION

### POWER SWITCH

The power switch is an N-channel MOSFET with a maximum on-state resistance of 50 m $\Omega$  ( $V_{I(IN)} = 5V$ ). Configured as a high-side switch, the power switch prevents current flow from OUT to IN and IN to OUT when disabled.

### CHARGE PUMP

An internal charge pump supplies power to the driver circuit and provides the necessary voltage to pull the gate of the MOSFET above the source. The charge pump operates from input voltages as low as 2.7 V and requires very little supply current.

### DRIVER

The driver controls the gate voltage of the power switch. To limit large current surges and reduce the associated electromagnetic interference (EMI) produced, the driver incorporates circuitry that controls the rise times and fall times of the output voltage. The rise and fall times are typically in the 2-ms to 9-ms range.

### ENABLE ( $\overline{EN}$ )

The logic enable disables the power switch, the bias for the charge pump, driver, and other circuitry to reduce the supply current to less than 10  $\mu A$  when a logic high is present on  $\overline{EN}$ . A logic zero input on  $\overline{EN}$  restores bias to the drive and control circuits and turns the power on. The enable input is compatible with both TTL and CMOS logic levels.

### CURRENT SENSE

A sense FET monitors the current supplied to the load. The sense FET measures current more efficiently than conventional resistance methods. When an overload or short circuit is encountered, the current-sense circuitry sends a control signal to the driver. The driver, in turn, reduces the gate voltage and drives the power FET into its saturation region, which switches the output into a constant current mode and holds the current constant while varying the voltage on the load.

### THERMAL SENSE

An internal thermal-sense circuit shuts off the power switch when the junction temperature rises to approximately 140°C. Hysteresis is built into the thermal sense circuit. After the device has cooled approximately 20°C, the switch turns back on. The switch continues to cycle off and on until the fault is removed.

### UNDERVOLTAGE LOCKOUT

A voltage sense circuit monitors the input voltage. When the input voltage is below approximately 2 V, a control signal turns off the power switch.

## ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

|              |                                                                        | VALUE                        | UNIT |
|--------------|------------------------------------------------------------------------|------------------------------|------|
| $V_{I(IN)}$  | Input voltage range <sup>(2)</sup>                                     | –0.3 to 6                    | V    |
| $V_{O(OUT)}$ | Output voltage range <sup>(2)</sup>                                    | –0.3 to $V_{I(IN)} + 0.3$    | V    |
| $V_{I(EN)}$  | Input voltage range                                                    | –0.3 to 6                    | V    |
| $I_{O(OUT)}$ | Continuous output current                                              | Internally Limited           |      |
|              | Continuous total power dissipation                                     | See Dissipation Rating Table |      |
| $T_J$        | Operating virtual junction temperature range                           | –40 to 125                   | °C   |
| $T_{stg}$    | Storage temperature range                                              | –65 to 150                   | °C   |
|              | Lead temperature soldering 1,6 mm (1/16 inch) from case for 10 seconds | 260                          | °C   |
| ESD          | Electrostatic discharge protection                                     | Human body model             | kV   |
|              |                                                                        | Machine model                | V    |

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to GND.

## DISSIPATION RATINGS

| PACKAGE | $T_A \leq 25^\circ\text{C}$<br>POWER RATING | DERATING FACTOR<br>ABOVE $T_A = 25^\circ\text{C}$ | $T_A = 70^\circ\text{C}$<br>POWER RATING | $T_A = 85^\circ\text{C}$<br>POWER RATING |
|---------|---------------------------------------------|---------------------------------------------------|------------------------------------------|------------------------------------------|
| D       | 725 mW                                      | 5.8 mW/°C                                         | 464 mW                                   | 377 mW                                   |
| PWP     | 700 mW                                      | 5.6 mW/°C                                         | 448 mW                                   | 364 mW                                   |

## RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

|             |                                        | MIN      | MAX | UNIT |
|-------------|----------------------------------------|----------|-----|------|
| $V_{I(IN)}$ | Input voltage                          | 2.7      | 5.5 | V    |
| $V_{IH}$    |                                        | 0        | 5.5 |      |
| $I_O$       | Continuous output current              | TPS2010A | 0   | 0.2  |
|             |                                        | TPS2011A | 0   | 0.6  |
|             |                                        | TPS2012A | 0   | 1    |
|             |                                        | TPS2013A | 0   | 1.5  |
| $T_J$       | Operating virtual junction temperature | –40      | 125 | °C   |

## ELECTRICAL CHARACTERISTICS

over recommended operating junction temperature range,  $V_{I(IN)} = 5.5\text{ V}$ ,  $I_O = \text{rated current}$ ,  $\overline{EN} = 0\text{ V}$  (unless otherwise noted)

| PARAMETER                               |                                         | TEST CONDITIONS <sup>(1)</sup>                                                                                 |          |          |     | MIN  | TYP | MAX | UNIT |
|-----------------------------------------|-----------------------------------------|----------------------------------------------------------------------------------------------------------------|----------|----------|-----|------|-----|-----|------|
| POWER SWITCH                            |                                         |                                                                                                                |          |          |     |      |     |     |      |
| r <sub>DS(on)</sub>                     | Static drain-source on-state resistance | V <sub>I(IN)</sub> = 5 V,      T <sub>J</sub> = 25°C,      I <sub>O</sub> = 1.5 A                              | TPS2013A |          |     | 33   | 36  | mΩ  |      |
|                                         |                                         | V <sub>I(IN)</sub> = 5 V,      T <sub>J</sub> = 85°C,      I <sub>O</sub> = 1.5 A                              |          |          |     | 38   | 46  |     |      |
|                                         |                                         | V <sub>I(IN)</sub> = 5 V,      T <sub>J</sub> = 125°C,      I <sub>O</sub> = 1.5 A                             |          |          |     | 44   | 50  |     |      |
|                                         |                                         | V <sub>I(IN)</sub> = 3.3 V,      T <sub>J</sub> = 25°C,      I <sub>O</sub> = 1.5 A                            |          |          |     | 37   | 41  |     |      |
|                                         |                                         | V <sub>I(IN)</sub> = 3.3 V,      T <sub>J</sub> = 85°C,      I <sub>O</sub> = 1.5 A                            |          |          |     | 43   | 52  |     |      |
|                                         |                                         | V <sub>I(IN)</sub> = 3.3 V,      T <sub>J</sub> = 125°C,      I <sub>O</sub> = 1.5 A                           |          |          |     | 51   | 61  |     |      |
|                                         |                                         | V <sub>I(IN)</sub> = 5 V,      T <sub>J</sub> = 25°C,      I <sub>O</sub> = 0.18 A                             | TPS2010A |          |     | 30   | 34  | mΩ  |      |
|                                         |                                         | V <sub>I(IN)</sub> = 5 V,      T <sub>J</sub> = 85°C,      I <sub>O</sub> = 0.18 A                             |          |          |     | 35   | 41  |     |      |
|                                         |                                         | V <sub>I(IN)</sub> = 5 V,      T <sub>J</sub> = 125°C,      I <sub>O</sub> = 0.18 A                            |          |          |     | 39   | 47  |     |      |
|                                         |                                         | V <sub>I(IN)</sub> = 3.3 V,      T <sub>J</sub> = 25°C,      I <sub>O</sub> = 0.18 A                           |          |          |     | 33   | 37  |     |      |
|                                         |                                         | V <sub>I(IN)</sub> = 3.3 V,      T <sub>J</sub> = 85°C,      I <sub>O</sub> = 0.18 A                           |          |          |     | 39   | 46  |     |      |
|                                         |                                         | V <sub>I(IN)</sub> = 3.3 V,      T <sub>J</sub> = 125°C,      I <sub>O</sub> = 0.18 A                          |          |          |     | 44   | 56  |     |      |
| t <sub>r</sub>                          | Rise time, output                       | V <sub>I(IN)</sub> = 5.5 V,      T <sub>J</sub> = 25°C,      C <sub>L</sub> = 1 μF,      R <sub>L</sub> = 10 Ω |          |          | 6.1 |      | ms  |     |      |
|                                         |                                         | V <sub>I(IN)</sub> = 2.7 V,      T <sub>J</sub> = 25°C,      C <sub>L</sub> = 1 μF,      R <sub>L</sub> = 10 Ω |          |          | 8.6 |      |     |     |      |
| t <sub>f</sub>                          | Rise time, output                       | V <sub>I(IN)</sub> = 5.5 V,      T <sub>J</sub> = 25°C,      C <sub>L</sub> = 1 μF,      R <sub>L</sub> = 10 Ω |          |          | 3.4 |      | ms  |     |      |
|                                         |                                         | V <sub>I(IN)</sub> = 2.7 V,      T <sub>J</sub> = 25°C,      C <sub>L</sub> = 1 μF,      R <sub>L</sub> = 10 Ω |          |          | 3   |      |     |     |      |
| ENABLE INPUT ( $\overline{\text{EN}}$ ) |                                         |                                                                                                                |          |          |     |      |     |     |      |
| V <sub>IH</sub>                         | High-level input voltage                | 2.7 V ≤ V <sub>I(IN)</sub> ≤ 5.5 V                                                                             |          |          |     | 2    |     |     | V    |
| V <sub>IL</sub>                         | Low-level input voltage                 | 4.5 V ≤ V <sub>I(IN)</sub> ≤ 5.5 V                                                                             |          |          |     |      |     | 0.8 | V    |
|                                         |                                         | 2.7 V ≤ V <sub>I(IN)</sub> ≤ 4.5 V                                                                             |          |          |     |      |     | 0.5 |      |
| I <sub>I</sub>                          | Input current                           | $\overline{\text{EN}}$ = 0 V or $\overline{\text{EN}}$ = V <sub>I(IN)</sub>                                    |          |          |     | −0.5 |     | 0.5 | μA   |
| t <sub>on</sub>                         | Turnon time                             | C <sub>L</sub> = 100 μF,      R <sub>L</sub> = 10 Ω                                                            |          |          |     |      |     | 20  | ms   |
| t <sub>off</sub>                        | Turnoff time                            | C <sub>L</sub> = 100 μF,      R <sub>L</sub> = 10 Ω                                                            |          |          |     |      |     | 40  | ms   |
| CURRENT LIMIT                           |                                         |                                                                                                                |          |          |     |      |     |     |      |
| I <sub>OS</sub>                         | Short-circuit output current            | T <sub>J</sub> = 25°C, V <sub>I</sub> = 5.5 V,<br>OUT connected to GND,<br>Device enable into short circuit    |          | TPS2010A |     | 0.22 | 0.3 | 0.4 | A    |
|                                         |                                         |                                                                                                                |          | TPS2011A |     | 0.66 | 0.9 | 1.1 |      |
|                                         |                                         |                                                                                                                |          | TPS2012A |     | 1.1  | 1.5 | 1.8 |      |
|                                         |                                         |                                                                                                                |          | TPS2013A |     | 1.65 | 2.2 | 2.7 |      |

(1) Pulse-testing techniques maintain junction temperature close to ambient temperature; thermal effects must be taken into account separately.

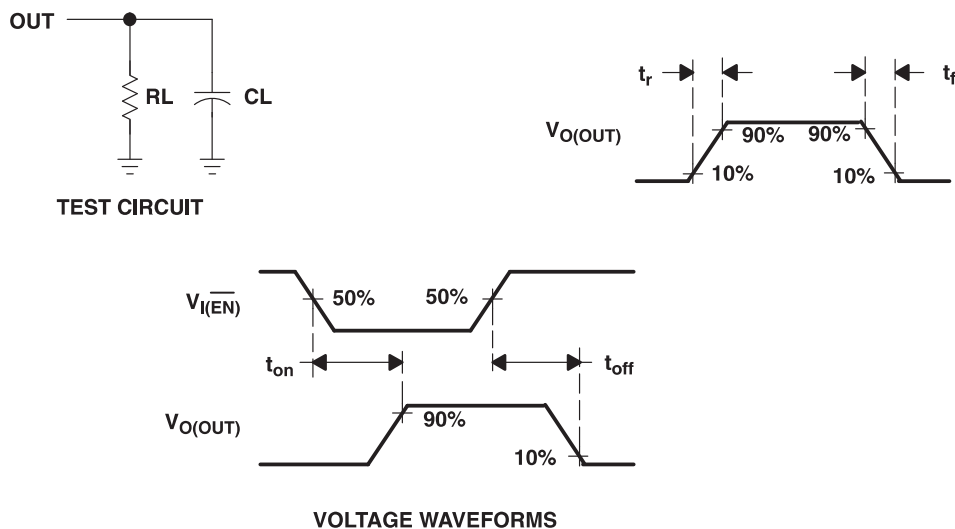
## ELECTRICAL CHARACTERISTICS (Continued)

over recommended operating junction temperature range,  $V_{I(IN)} = 5.5\text{ V}$ ,  $I_O$  = rated current,  $\overline{EN} = 0\text{ V}$  (unless otherwise noted)

| PARAMETER                         | TEST CONDITIONS <sup>(1)</sup>      |                                           |                                                                  | MIN | TYP | MAX           | UNIT |
|-----------------------------------|-------------------------------------|-------------------------------------------|------------------------------------------------------------------|-----|-----|---------------|------|
| SUPPLY CURRENT                    |                                     |                                           |                                                                  |     |     |               |      |
| Supply current, low-level output  | No Load on OUT                      | $\overline{\text{EN}} = V_{\text{I(IN)}}$ | $T_{\text{J}} = 25^{\circ}\text{C}$                              | 0.3 | 1   | $\mu\text{A}$ |      |
|                                   |                                     |                                           | $-40^{\circ}\text{C} \leq T_{\text{J}} \leq 125^{\circ}\text{C}$ |     | 10  |               |      |
| Supply current, high-level output | No Load on OUT                      | $\overline{\text{EN}} = 0\text{ V}$       | $T_{\text{J}} = 25^{\circ}\text{C}$                              | 58  | 75  | $\mu\text{A}$ |      |
|                                   |                                     |                                           | $-40^{\circ}\text{C} \leq T_{\text{J}} \leq 125^{\circ}\text{C}$ | 75  | 100 |               |      |
| Leakage current                   | OUT connected to ground             | $\overline{\text{EN}} = V_{\text{I(IN)}}$ | $-40^{\circ}\text{C} \leq T_{\text{J}} \leq 125^{\circ}\text{C}$ | 10  |     | $\mu\text{A}$ |      |
| UNDERVOLTAGE LOCKOUT              |                                     |                                           |                                                                  |     |     |               |      |
| Low-level input voltage           |                                     |                                           |                                                                  | 2   | 2.5 | V             |      |
| Hysteresis                        | $T_{\text{J}} = 25^{\circ}\text{C}$ |                                           |                                                                  | 100 |     | mV            |      |

- (1) Pulse-testing techniques maintain junction temperature close to ambient temperature; thermal effects must be taken into account separately.

## PARAMETER MEASUREMENT INFORMATION



**Figure 1. Test Circuit and Voltage Waveforms**

**Table 1. Timing Diagrams**

|                                                                           | FIGURE      |
|---------------------------------------------------------------------------|-------------|
| Turnon Delay and Rise Time                                                | 2           |
| Turnoff Delay and Fall Time                                               | 3           |
| Turnon Delay and Rise TIME with 1- $\mu$ F Load                           | 4           |
| Turnoff Delay and Rise TIME with 1- $\mu$ F Load                          | 5           |
| Device Enabled into Short                                                 | 6           |
| TPS2010A, TPS2011A, TPS2012A, and TPS2013A, Ramped Load on Enabled Device | 7, 8, 9, 10 |
| TPS2013A, Inrush Current                                                  | 11          |
| 7.9- $\Omega$ Load Connected to an Enabled TPS2010A Device                | 12          |
| 3.7- $\Omega$ Load Connected to an Enabled TPS2010A Device                | 13          |
| 3.7- $\Omega$ Load Connected to an Enabled TPS2011A Device                | 14          |
| 2.6- $\Omega$ Load Connected to an Enabled TPS2011A Device                | 15          |
| 2.6- $\Omega$ Load Connected to an Enabled TPS2012A Device                | 16          |
| 1.2- $\Omega$ Load Connected to an Enabled TPS2012A Device                | 17          |
| 1.2- $\Omega$ Load Connected to an Enabled TPS2013A Device                | 18          |
| 0.9- $\Omega$ Load Connected to an Enabled TPS2013A Device                | 19          |

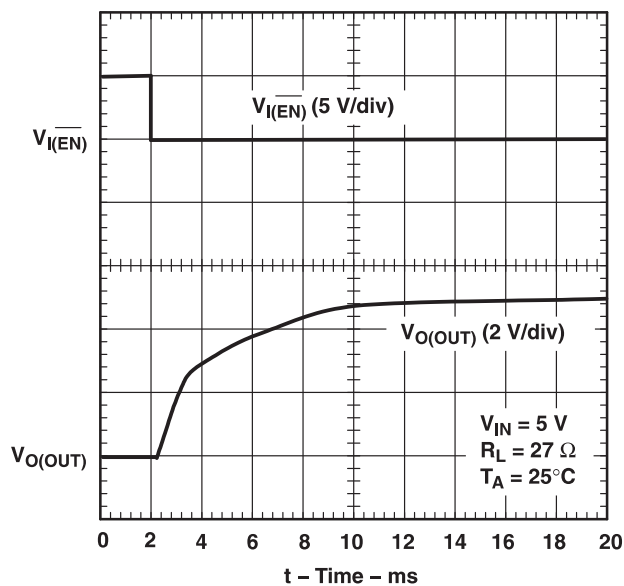


Figure 2. Turnon Delay and Rise Time

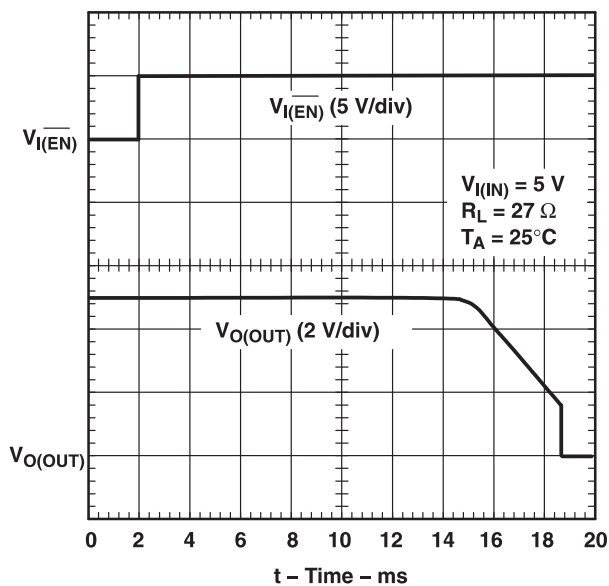


Figure 3. Turnoff Delay and Fall Time

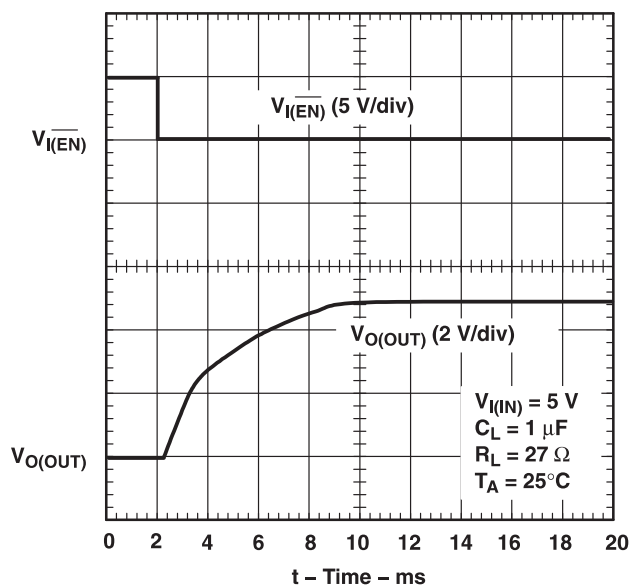


Figure 4. Turnon Delay and Rise Time With 1-μF Load

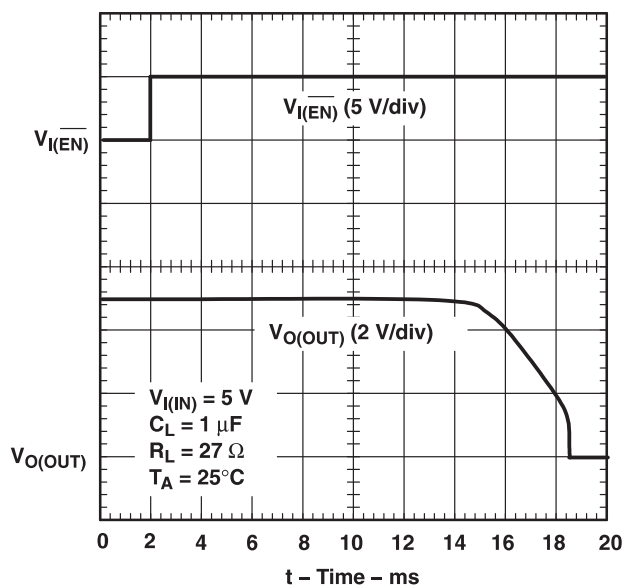


Figure 5. Turnoff Delay and Fall Time With 1-μF Load



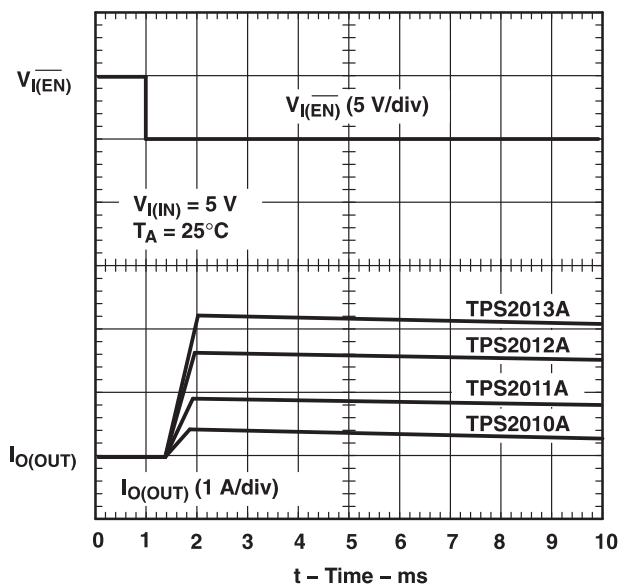


Figure 6. Device Enabled Into Short

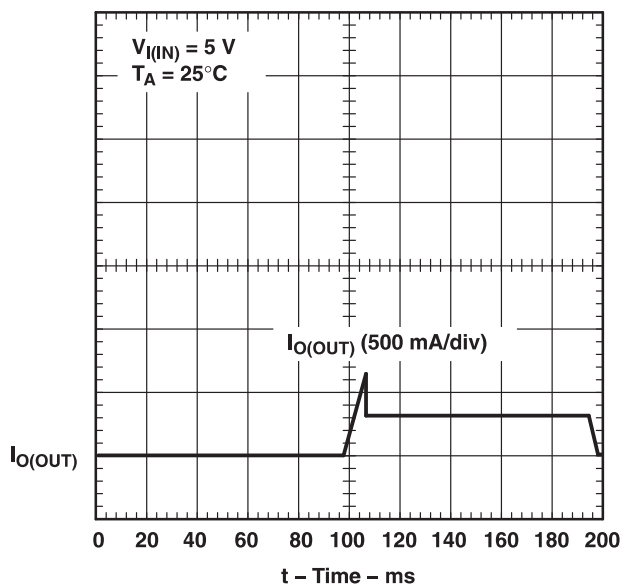


Figure 7. TPS2010A, Ramped Load on Enabled Device

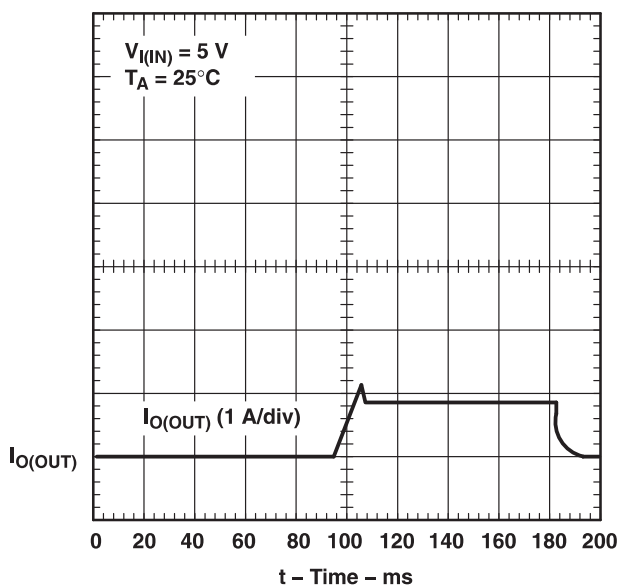


Figure 8. TPS2011A, Ramped Load on Enabled Device

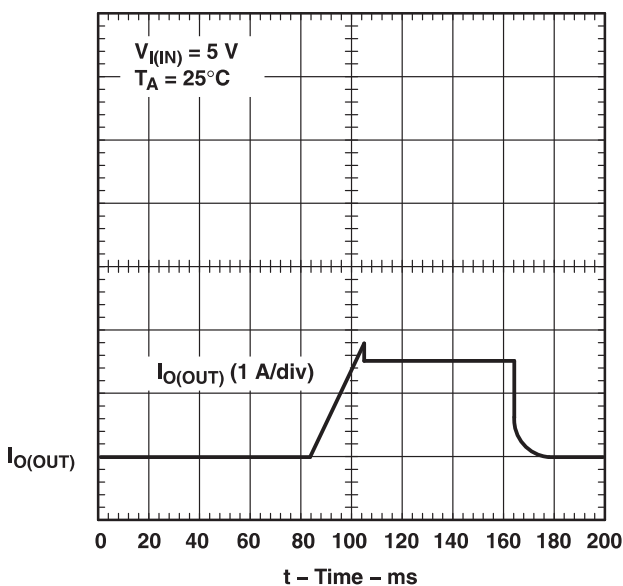


Figure 9. TPS2012A, Ramped Load on Enabled Device

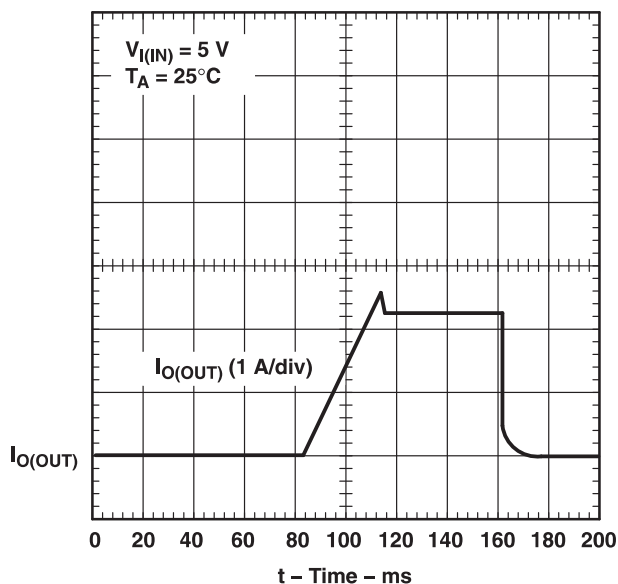


Figure 10. TPS2013A, Ramped Load on Enabled Device

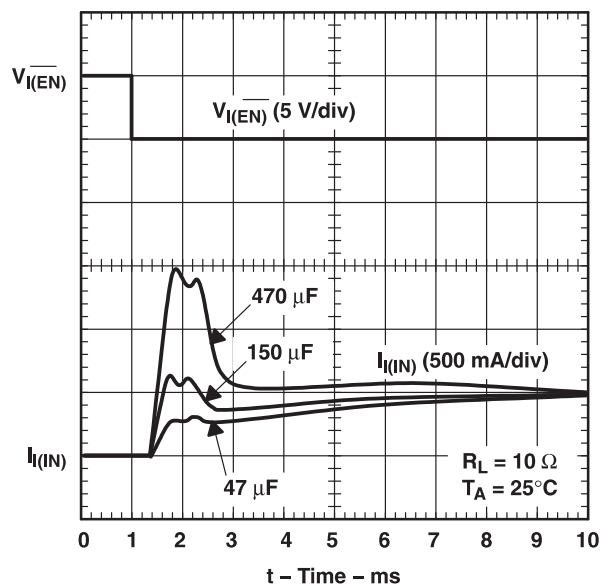


Figure 11. TPS2013A, Inrush Current

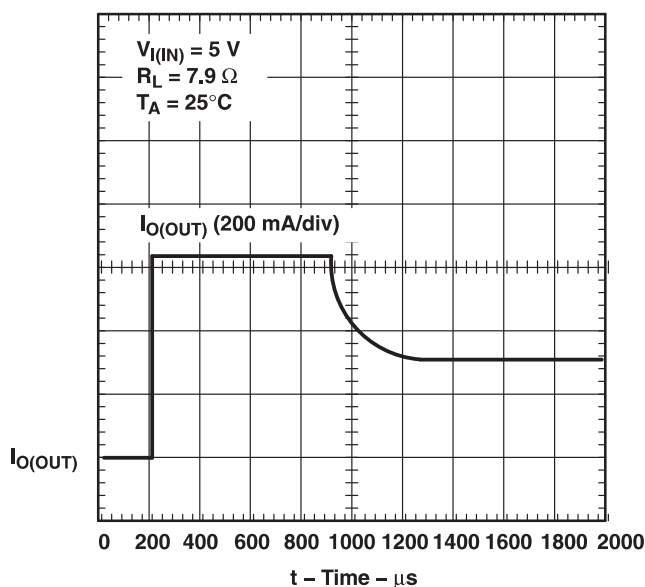


Figure 12. 7.9-Ω Load Connected to an Enabled TPS2010A Device

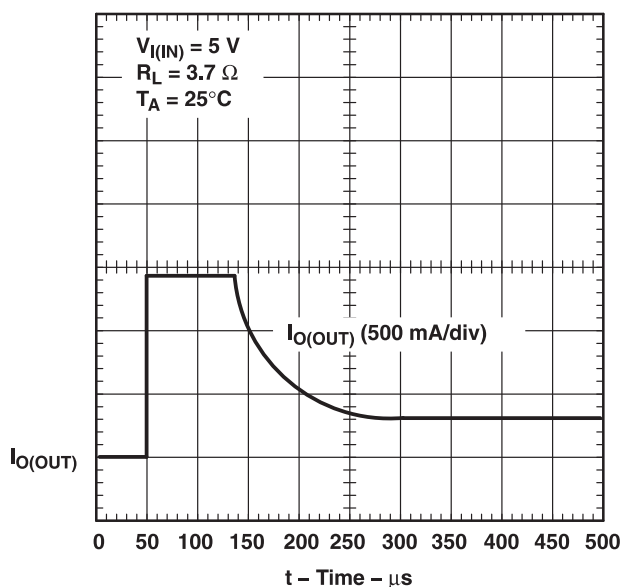


Figure 13. 3.7-Ω Load Connected to an Enabled TPS2010A Device

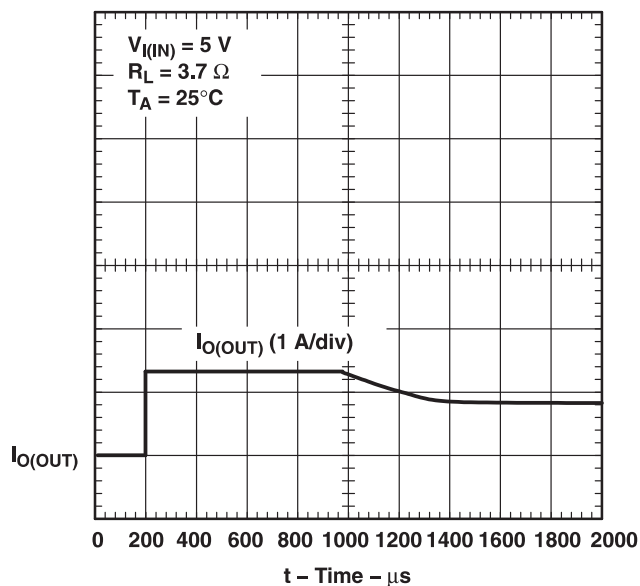


Figure 14. 3.7- $\Omega$  Load Connected to an Enabled TPS2011A Device

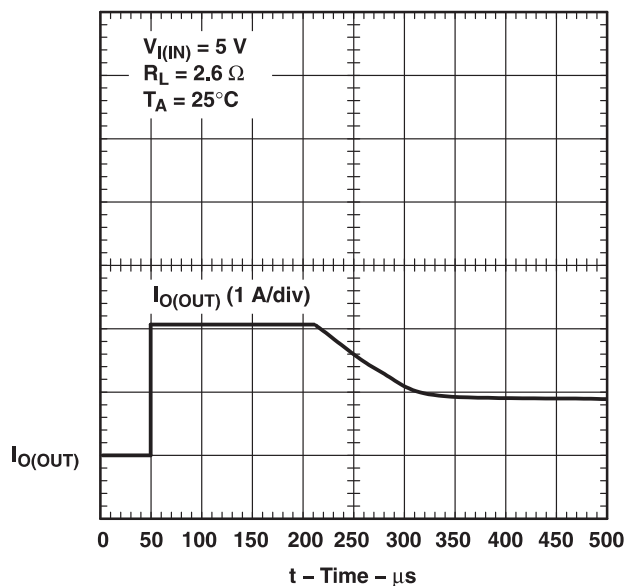


Figure 15. 2.6- $\Omega$  Load Connected to an Enabled TPS2011A Device

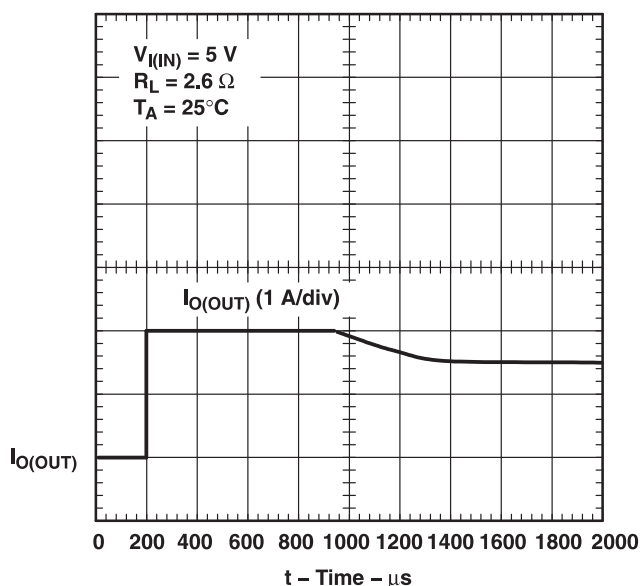


Figure 16. 2.6- $\Omega$  Load Connected to an Enabled TPS2012A Device

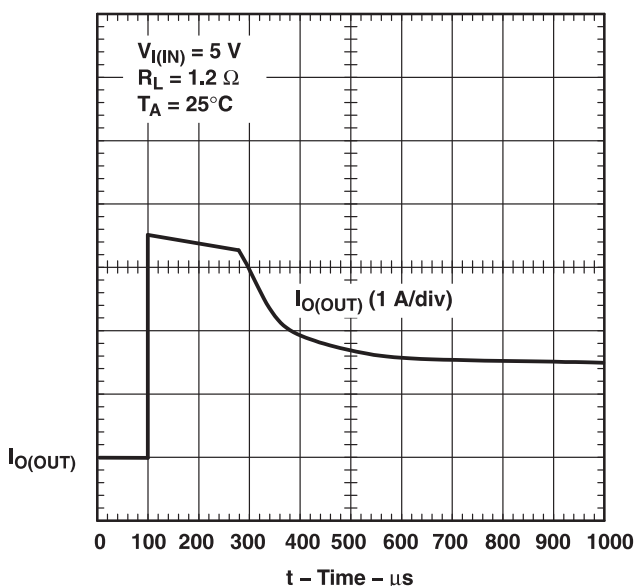


Figure 17. 1.2- $\Omega$  Load Connected to an Enabled TPS2012A Device

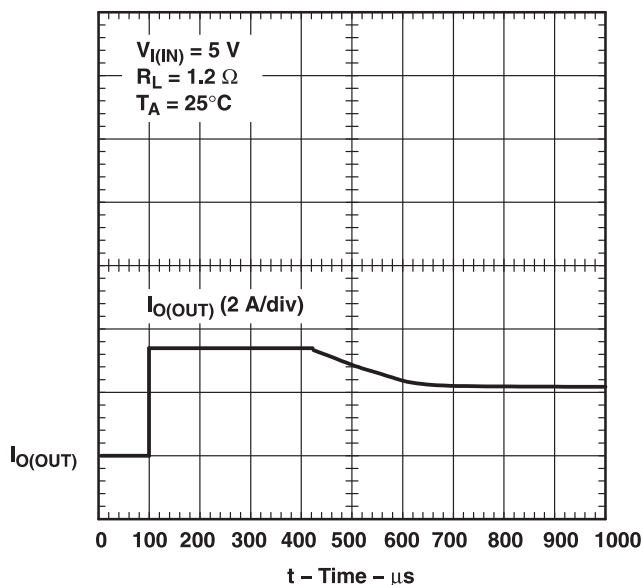


Figure 18. 1.2- $\Omega$  Load Connected to an Enabled TPS2013A Device

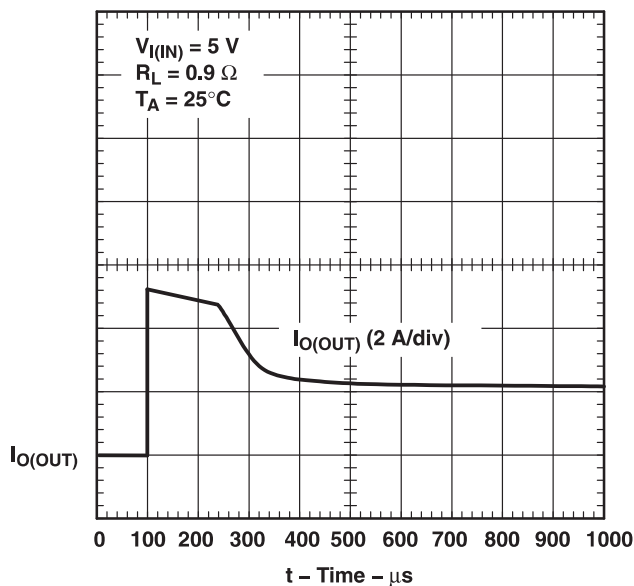


Figure 19. 0.9- $\Omega$  Load Connected to an Enabled TPS2013A Device

## TYPICAL CHARACTERISTICS

### Table of Graphs

|              |                                         |                              | FIGURE |
|--------------|-----------------------------------------|------------------------------|--------|
| $t_{d(on)}$  | Turnon delay time                       | vs Output voltage            | 20     |
| $t_{d(off)}$ | Turnoff delay time                      | vs Input voltage             | 21     |
| $t_r$        | Rise time                               | vs Load current              | 22     |
| $t_f$        | Fall time                               | vs Load current              | 23     |
|              | Supply current (enabled)                | vs Junction temperature      | 24     |
|              | Supply current (disabled)               | vs Junction temperature      | 25     |
|              | Supply current (enabled)                | vs Input voltage             | 26     |
|              | Supply current (disabled)               | vs Input voltage             | 27     |
| $I_{OS}$     | Short-circuit current limit             | vs Input voltage             | 28     |
|              |                                         | vs Junction temperature      | 29     |
| $r_{DS(on)}$ | Static drain-source on-state resistance | vs Input voltage             | 30     |
|              |                                         | vs Junction temperature      | 31     |
|              |                                         | vs Input voltage             | 32     |
|              |                                         | vs Junction temperature      | 33     |
|              | Undervoltage lockout                    | Input voltage vs Temperature | 34     |

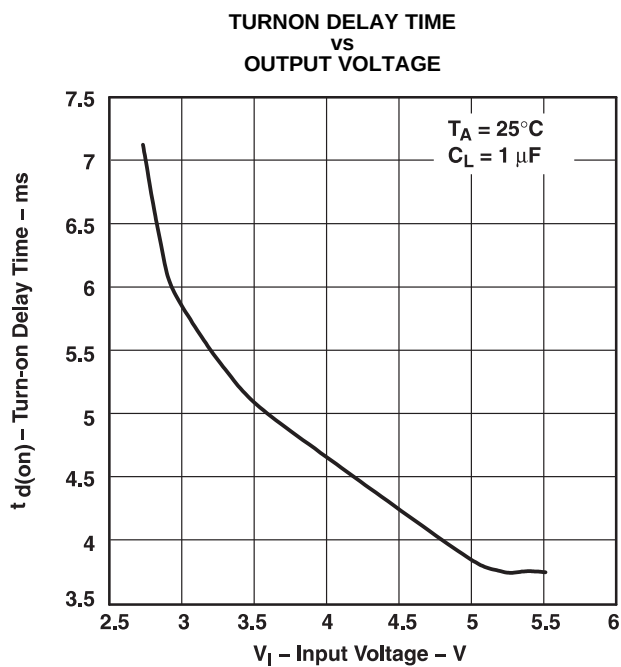


Figure 20.

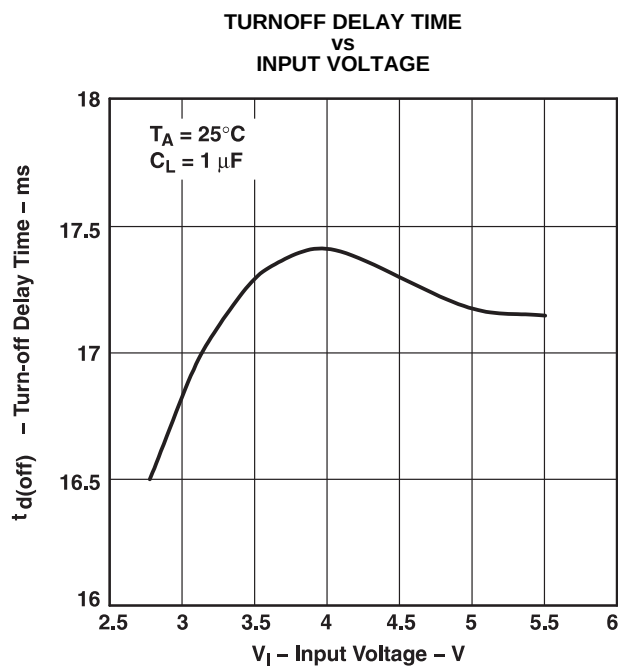


Figure 21.

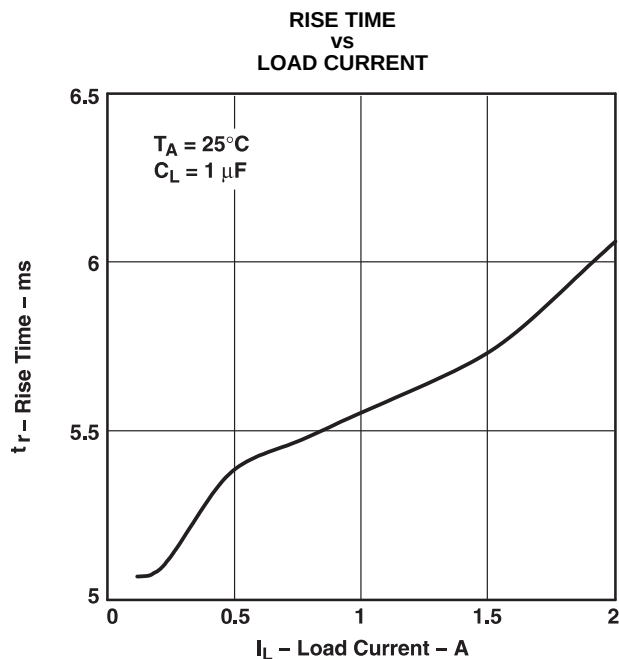


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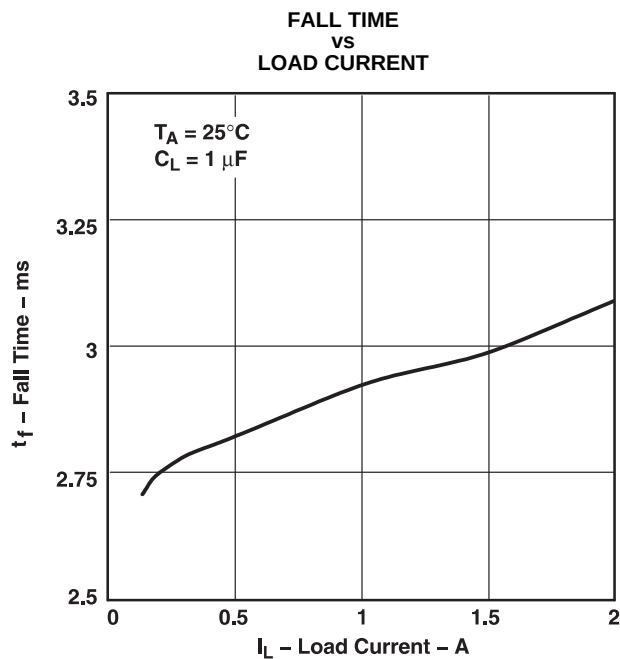


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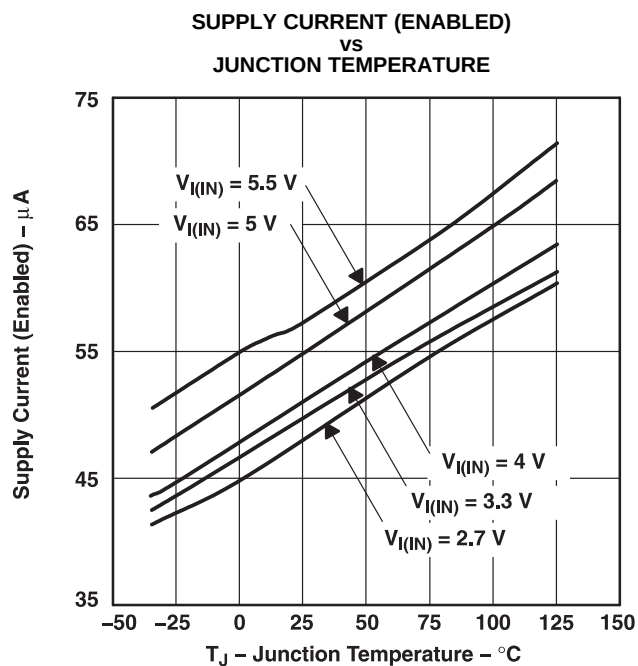


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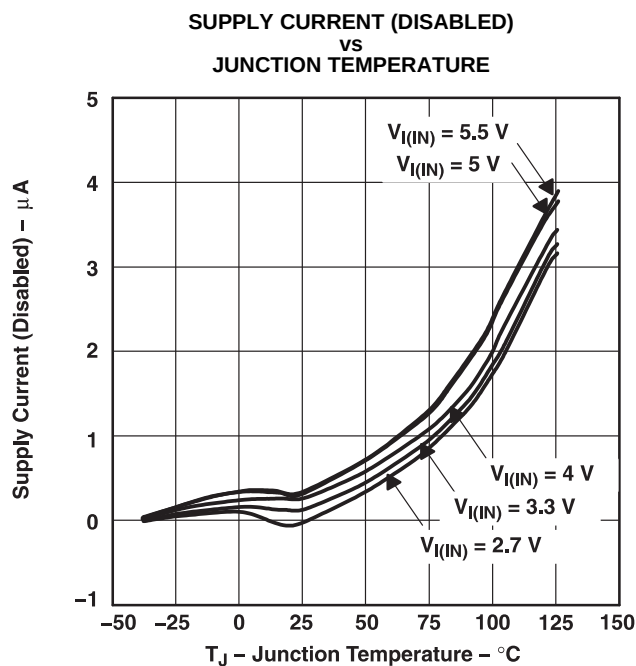


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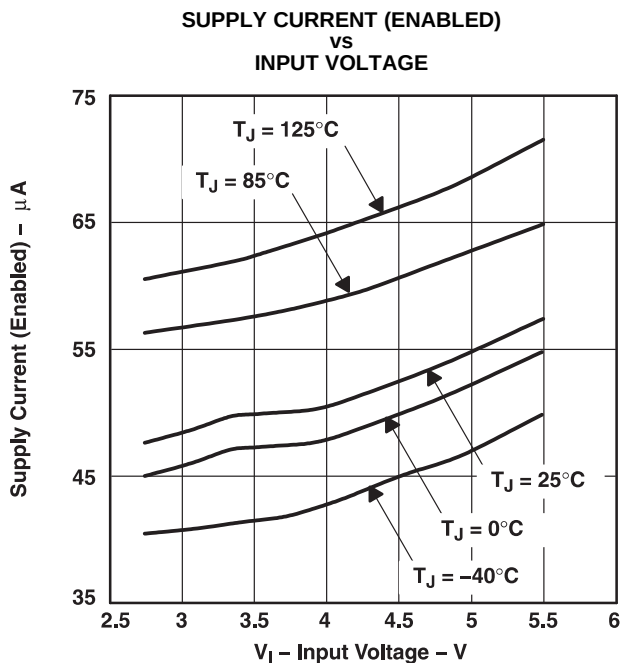


Figure 26.

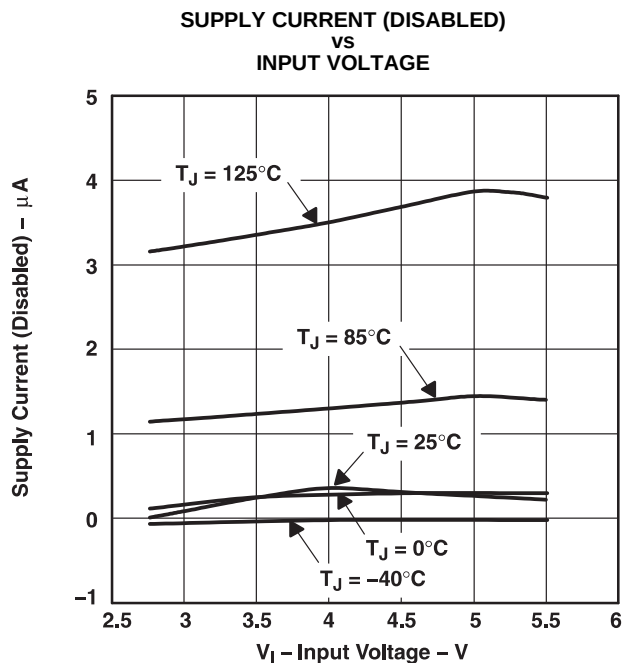


Figure 27.

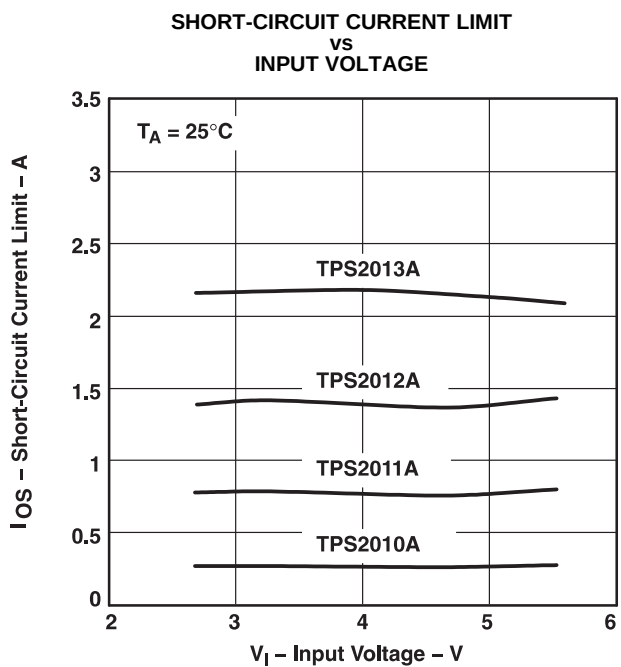


Figure 28.

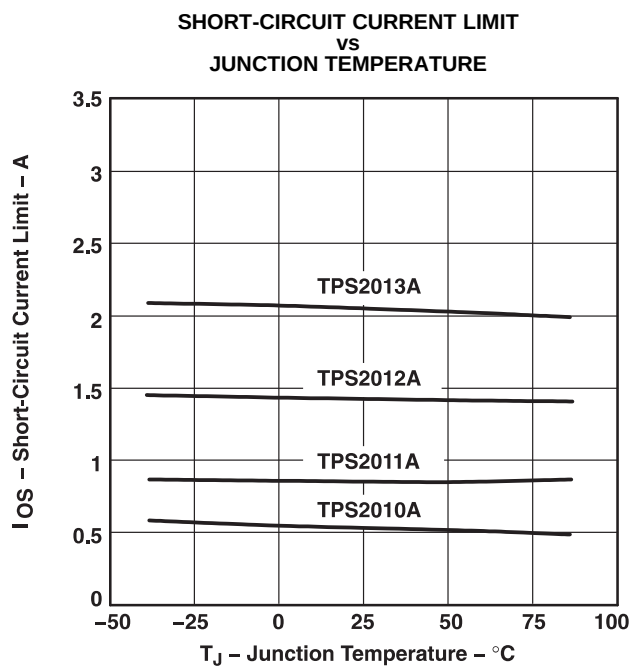


Figure 29.

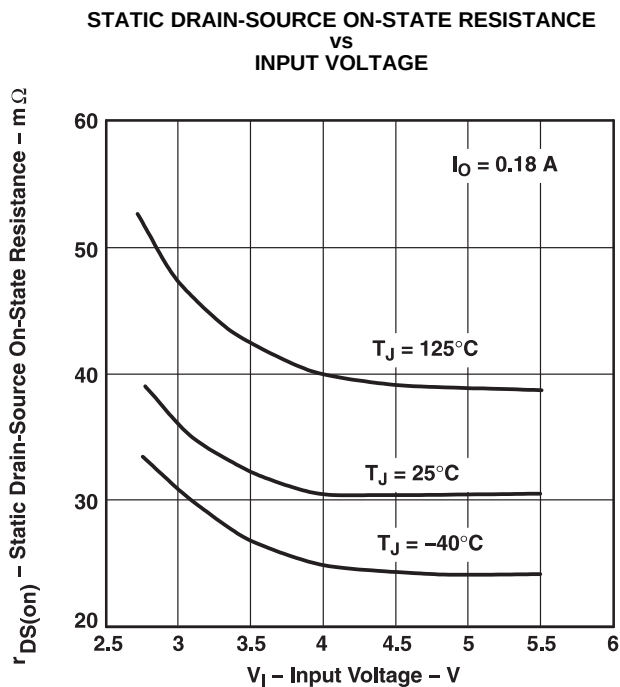


Figure 30.

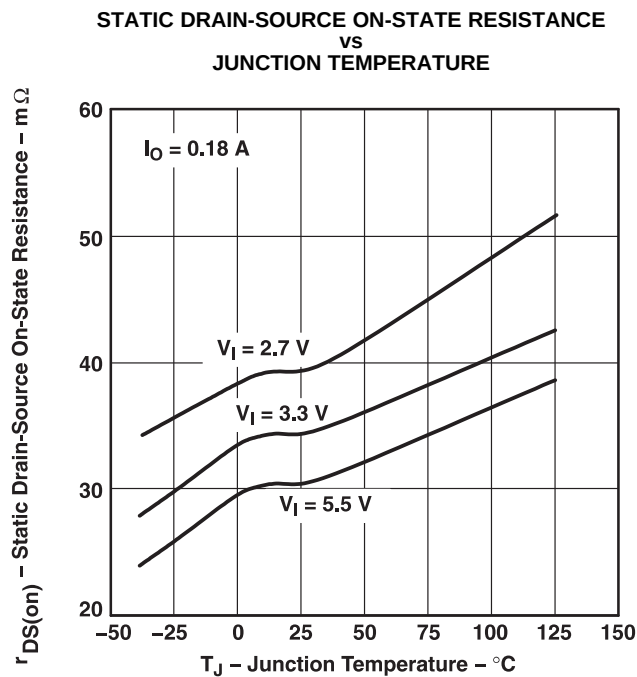


Figure 31.

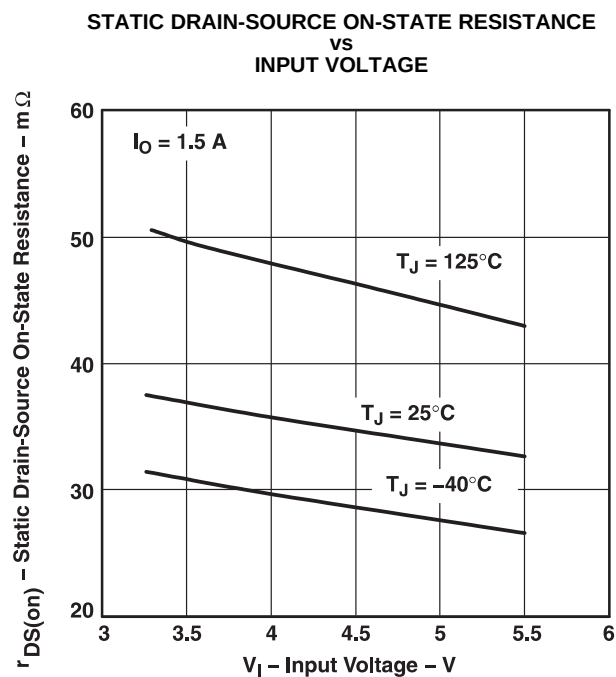


Figure 32.

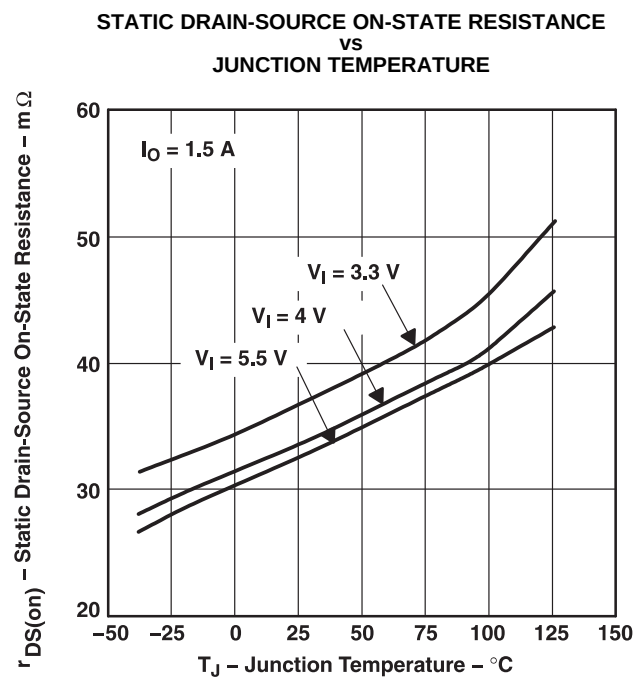


Figure 33.



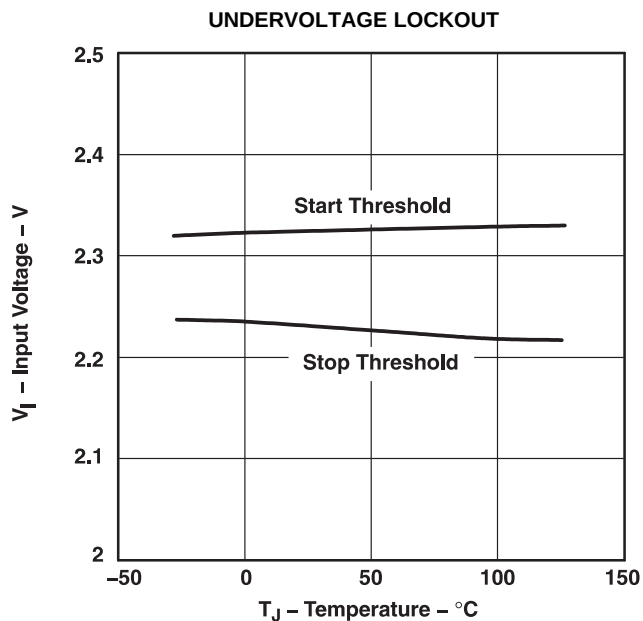


Figure 34.

## APPLICATION INFORMATION

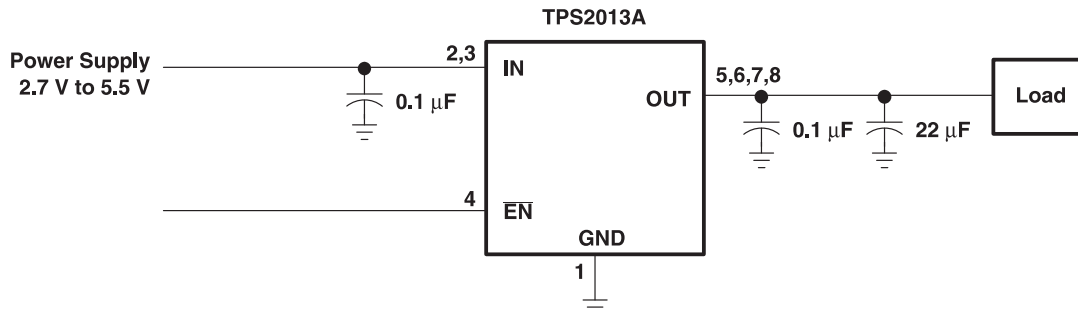


Figure 35. Typical Application

## POWER-SUPPLY CONSIDERATIONS

A 0.01-μF to 0.1-μF ceramic bypass capacitor between IN and GND, close to the device, is recommended. Placing a high-value electrolytic capacitor on the output and input pins is recommended when the output load is heavy. This precaution reduces power supply transients that may cause ringing on the input. Additionally, bypassing the output with a 0.01-μF to 0.1-μF ceramic capacitor improves the immunity of the device to short-circuit transients.

## OVERCURRENT

A sense FET checks for overcurrent conditions. Unlike current-sense resistors, sense FETs do not increase the series resistance of the current path. When an overcurrent condition is detected, the device maintains a constant output current and reduces the output voltage accordingly. Complete shutdown occurs only if the fault is present long enough to activate thermal limiting.

Three possible overload conditions can occur. In the first condition, the output has been shorted before the device is enabled or before  $V_{I(IN)}$  has been applied (see Figure 6). The TPS201xA senses the short and immediately switches into a constant-current output.

In the second condition, the excessive load occurs while the device is enabled. At the instant the excessive load occurs, very high currents may flow for a short time before the current-limit circuit can react (see Figure 12–Figure 19). After the current-limit circuit has tripped (reached the overcurrent trip threshold) the device switches into constant-current mode.

In the third condition, the load has been gradually increased beyond the recommended operating current. The current is permitted to rise until the current-limit threshold is reached or until the thermal limit of the device is exceeded (see Figures Figure 77–Figure 10). The TPS201xA is capable of delivering current up to the current-limit threshold without damaging the device. Once the threshold has been reached, the device switches into its constant-current mode.

## POWER DISSIPATION AND JUNCTION TEMPERATURE

The low on-resistance on the n-channel MOSFET allows small surface-mount packages, such as SOIC, to pass large currents. The thermal resistance of these packages are high compared to those of power packages; it is good design practice to check power dissipation and junction temperature. The first step is to find  $r_{DS(on)}$  at the input voltage and operating temperature. As an initial estimate, use the highest operating ambient temperature of interest and read  $r_{DS(on)}$  from SLVS1892074 Figure 30–Figure 33. Next, calculate the power dissipation using:

$$P_D = r_{DS(on)} \times I^2 \quad (1)$$

Finally, calculate the junction temperature:

$$T_J = P_D \times R_{\theta JA} + T_A \quad (2)$$

Where:

$T_A$  = Ambient Temperature °C

$R_{\theta JA}$  = Thermal resistance SOIC = 172°C/W

Compare the calculated junction temperature with the initial estimate. If they do not agree within a few degrees, repeat the calculation, using the calculated value as the new estimate. Two or three iterations are generally sufficient to get an acceptable answer.

## THERMAL PROTECTION

Thermal protection prevents damage to the IC when heavy-overload or short-circuit faults are present for extended periods of time. The faults force the TPS201xA into constant current mode, which causes the voltage across the high-side switch to increase; under short-circuit conditions, the voltage across the switch is equal to the input voltage. The increased dissipation causes the junction temperature to rise to high levels. The protection circuit senses the junction temperature of the switch and shuts it off. Hysteresis is built into the thermal sense circuit, and after the device has cooled approximately 20 degrees, the switch turns back on. The switch continues to cycle in this manner until the load fault or input power is removed.

## UNDERVOLTAGE LOCKOUT (UVLO)

An undervoltage lockout ensures that the power switch is in the off state at power up. Whenever the input voltage falls below approximately 2 V, the power switch will be quickly turned off. This facilitates the design of hot-insertion systems where it is not possible to turn off the power switch before input power is removed. The UVLO will also keep the switch from being turned on until the power supply has reached at least 2 V, even if the switch is enabled. Upon reinsertion, the power switch will be turned on, with a controlled rise time to reduce EMI and voltage overshoots.

## GENERIC HOT-PLUG APPLICATIONS (see Figure 36)

In many applications it may be necessary to remove modules or p-c boards while the main unit is still operating. These are considered hot-plug applications. Such implementations require the control of current surges seen by the main power supply and the card being inserted. The most effective way to control these surges is to limit and slowly ramp the current and voltage being applied to the card, similar to the way in which a power supply normally turns on. Because of the controlled rise times and fall times of the TPS201xA series, these devices can be used to provide a softer start-up to devices being hot-plugged into a powered system. The UVLO feature of the TPS201xA also ensures the switch will be off after the card has been removed, and the switch will be off during the next insertion. The UVLO feature guarantees a soft start with a controlled rise time for every insertion of the card or module.

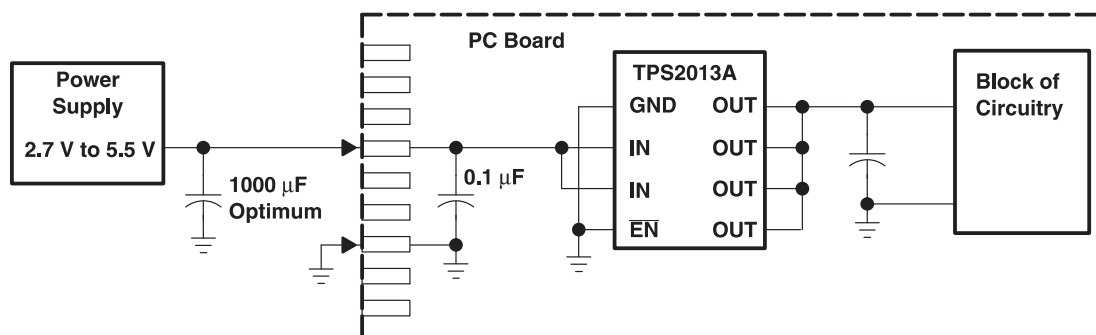


Figure 36. Typical Hot-Plug Implementation

By placing the TPS201xA between the  $V_{CC}$  input and the rest of the circuitry, the input power will reach this device first after insertion. The typical rise time of the switch is approximately 9 ms, providing a slow voltage ramp at the output of the device. This implementation controls system surge currents and provides a hot-plugging mechanism for any device.

## PACKAGING INFORMATION

| Orderable part number      | Status<br>(1) | Material type<br>(2) | Package   Pins | Package qty   Carrier | RoHS<br>(3) | Lead finish/<br>Ball material<br>(4) | MSL rating/<br>Peak reflow<br>(5) | Op temp (°C) | Part marking<br>(6) |
|----------------------------|---------------|----------------------|----------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|---------------------|
| <a href="#">TPS2010AD</a>  | Active        | Production           | SOIC (D)   8   | 75   TUBE             | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2010A               |
| TPS2010AD.A                | Active        | Production           | SOIC (D)   8   | 75   TUBE             | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2010A               |
| <a href="#">TPS2010ADR</a> | Active        | Production           | SOIC (D)   8   | 2500   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2010A               |
| TPS2010ADR.A               | Active        | Production           | SOIC (D)   8   | 2500   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2010A               |
| <a href="#">TPS2011AD</a>  | Active        | Production           | SOIC (D)   8   | 75   TUBE             | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2011A               |
| TPS2011AD.A                | Active        | Production           | SOIC (D)   8   | 75   TUBE             | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2011A               |
| <a href="#">TPS2011ADR</a> | Active        | Production           | SOIC (D)   8   | 2500   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2011A               |
| TPS2011ADR.A               | Active        | Production           | SOIC (D)   8   | 2500   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2011A               |
| TPS2011ADRG4               | Active        | Production           | SOIC (D)   8   | 2500   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2011A               |
| <a href="#">TPS2012AD</a>  | Active        | Production           | SOIC (D)   8   | 75   TUBE             | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2012A               |
| TPS2012AD.A                | Active        | Production           | SOIC (D)   8   | 75   TUBE             | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2012A               |
| <a href="#">TPS2012ADR</a> | Active        | Production           | SOIC (D)   8   | 2500   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2012A               |
| TPS2012ADR.A               | Active        | Production           | SOIC (D)   8   | 2500   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2012A               |
| <a href="#">TPS2013AD</a>  | Active        | Production           | SOIC (D)   8   | 75   TUBE             | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2013A               |
| TPS2013AD.A                | Active        | Production           | SOIC (D)   8   | 75   TUBE             | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2013A               |
| <a href="#">TPS2013ADR</a> | Active        | Production           | SOIC (D)   8   | 2500   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2013A               |
| TPS2013ADR.A               | Active        | Production           | SOIC (D)   8   | 2500   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | 2013A               |

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

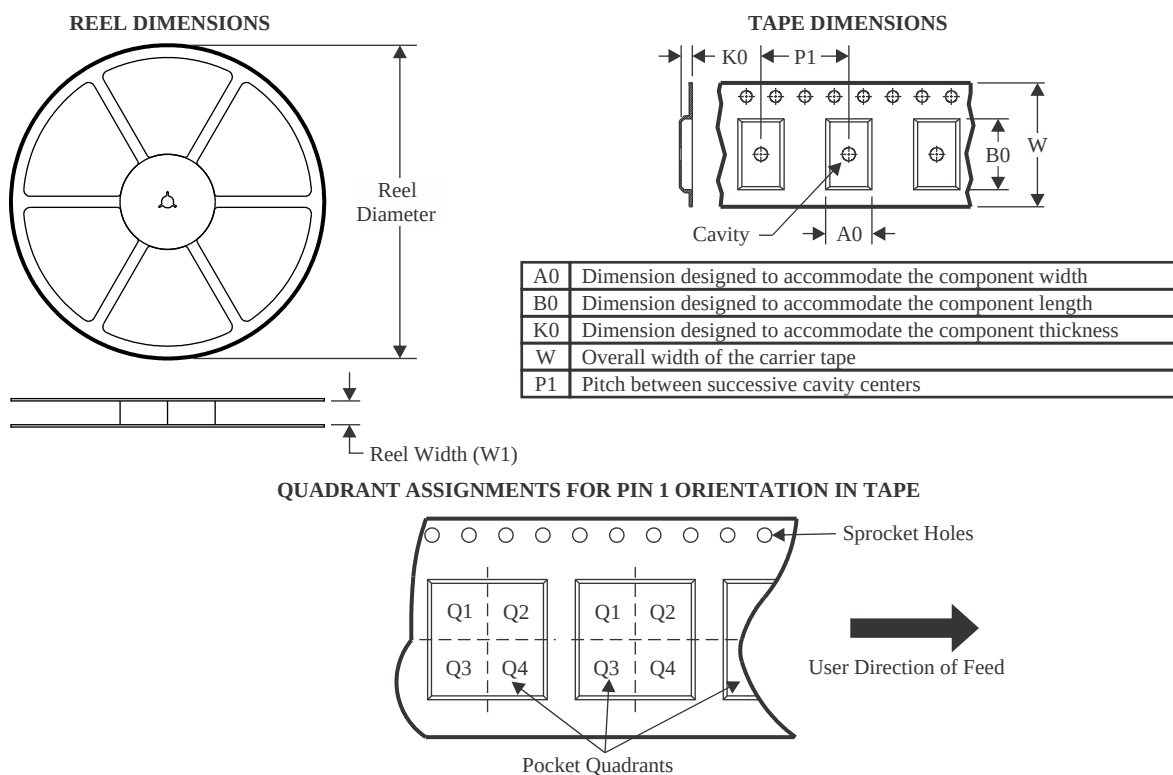
**(6) Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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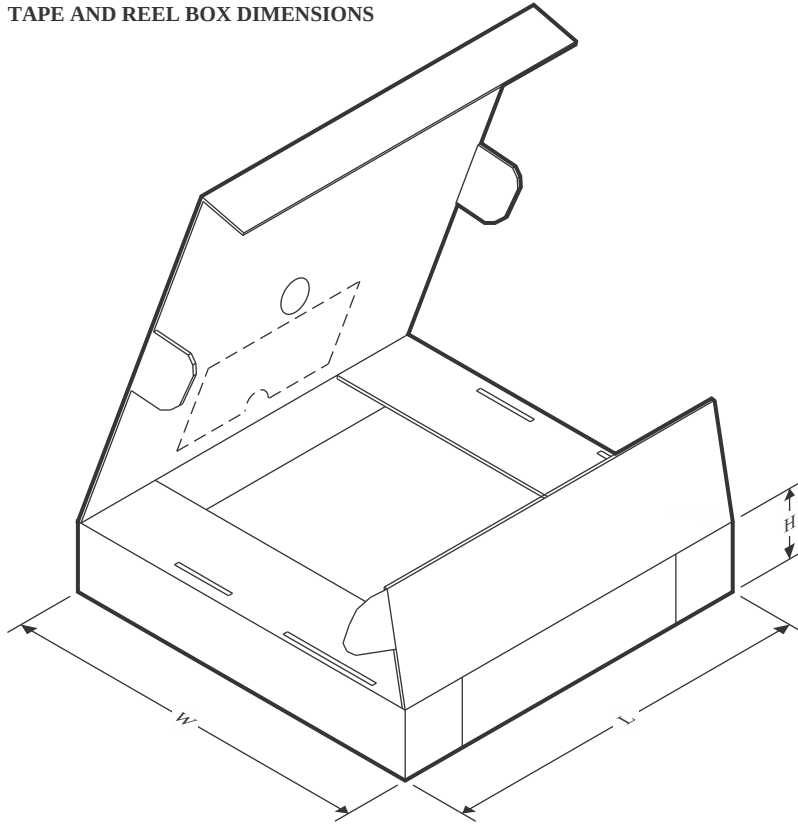
## TAPE AND REEL INFORMATION



\*All dimensions are nominal

| Device     | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TPS2010ADR | SOIC         | D               | 8    | 2500 | 330.0              | 12.4               | 6.4     | 5.2     | 2.1     | 8.0     | 12.0   | Q1            |
| TPS2011ADR | SOIC         | D               | 8    | 2500 | 330.0              | 12.4               | 6.4     | 5.2     | 2.1     | 8.0     | 12.0   | Q1            |
| TPS2012ADR | SOIC         | D               | 8    | 2500 | 330.0              | 12.4               | 6.4     | 5.2     | 2.1     | 8.0     | 12.0   | Q1            |
| TPS2013ADR | SOIC         | D               | 8    | 2500 | 330.0              | 12.4               | 6.4     | 5.2     | 2.1     | 8.0     | 12.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device     | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TPS2010ADR | SOIC         | D               | 8    | 2500 | 353.0       | 353.0      | 32.0        |
| TPS2011ADR | SOIC         | D               | 8    | 2500 | 353.0       | 353.0      | 32.0        |
| TPS2012ADR | SOIC         | D               | 8    | 2500 | 353.0       | 353.0      | 32.0        |
| TPS2013ADR | SOIC         | D               | 8    | 2500 | 353.0       | 353.0      | 32.0        |

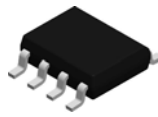
## TUBE



\*All dimensions are nominal

| Device      | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (μm) | B (mm) |
|-------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| TPS2010AD   | D            | SOIC         | 8    | 75  | 507    | 8      | 3940   | 4.32   |
| TPS2010AD.A | D            | SOIC         | 8    | 75  | 507    | 8      | 3940   | 4.32   |
| TPS2011AD   | D            | SOIC         | 8    | 75  | 507    | 8      | 3940   | 4.32   |
| TPS2011AD.A | D            | SOIC         | 8    | 75  | 507    | 8      | 3940   | 4.32   |
| TPS2012AD   | D            | SOIC         | 8    | 75  | 507    | 8      | 3940   | 4.32   |
| TPS2012AD.A | D            | SOIC         | 8    | 75  | 507    | 8      | 3940   | 4.32   |
| TPS2013AD   | D            | SOIC         | 8    | 75  | 507    | 8      | 3940   | 4.32   |
| TPS2013AD.A | D            | SOIC         | 8    | 75  | 507    | 8      | 3940   | 4.32   |



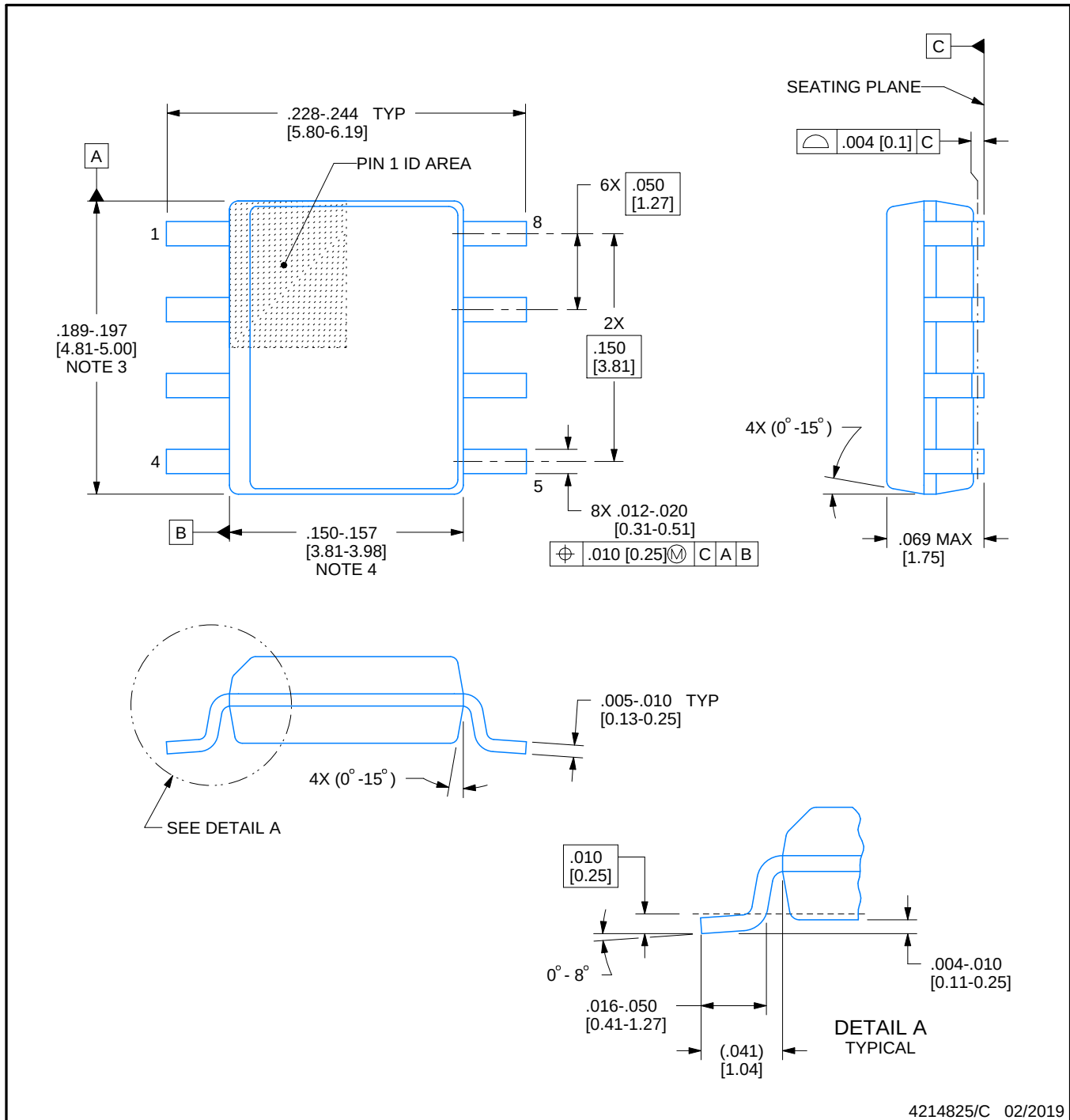


**D0008A**

# PACKAGE OUTLINE

**SOIC - 1.75 mm max height**

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

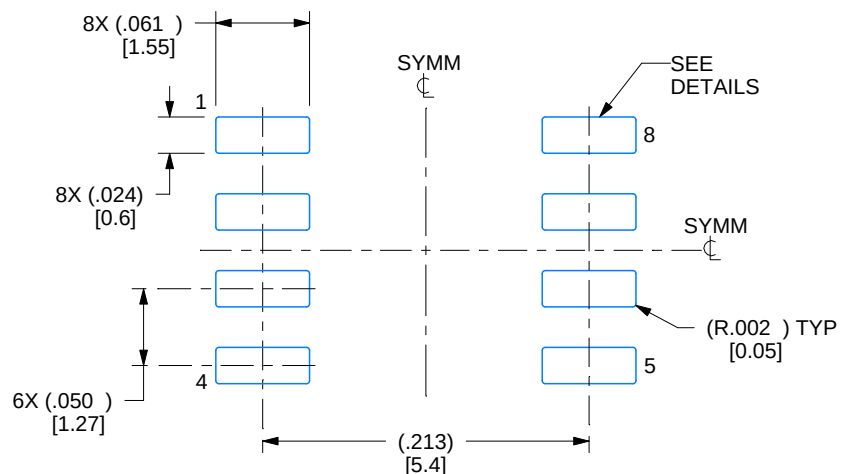
## NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

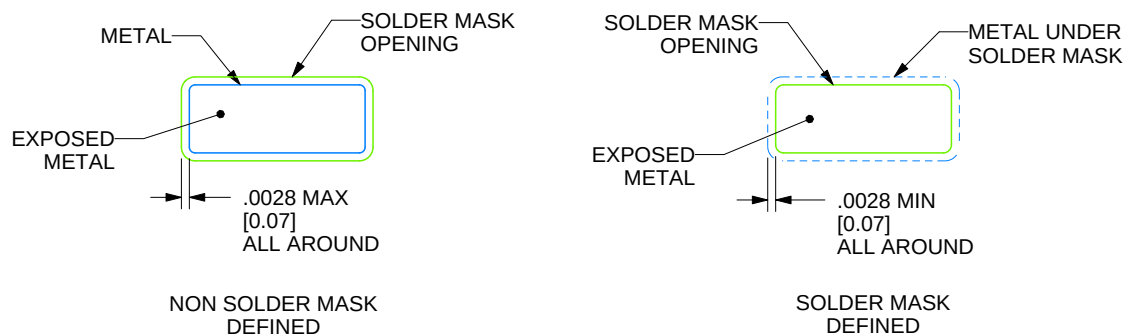
**D0008A**

**SOIC - 1.75 mm max height**

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:8X



## SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

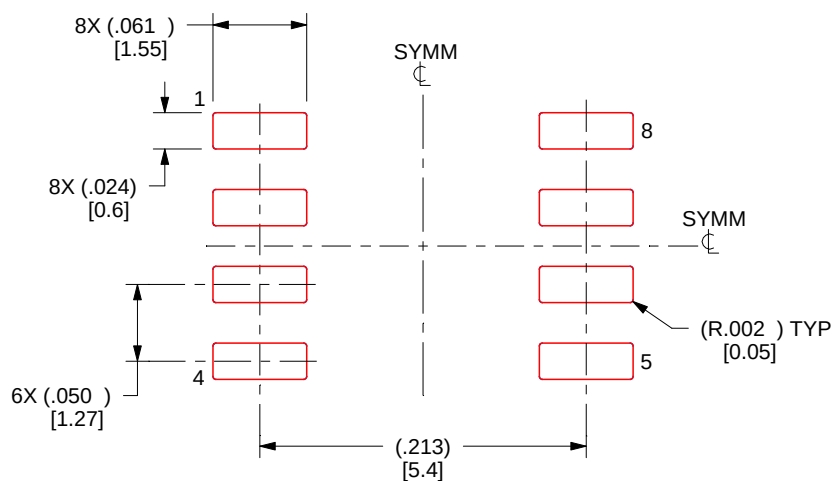
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON .005 INCH [0.125 MM] THICK STENCIL  
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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